

#### Description

The HXY50P02D uses advanced trench technology

to provide excellent  $R_{DS(ON)}$ , low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = -20V I<sub>D</sub> =-50A

 $R_{DS(ON)} < 18 \text{ m}\Omega @ V_{GS}=4.5V$ 

#### Application

Battery protection

Load switch

Uninterruptible power supply

#### Package Marking and Ordering Information

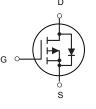
Product ID	Pack	Marking	Qty(PCS)
HXY50P02D	TO252-2L	50P02 XXX YYYY	2500

#### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	Drain-Source Voltage -20		
VGS	Gate-Source Voltage	Gate-Source Voltage ±12		
I⊳@Tc=25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	ous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> -50		
I⊳@Tc=100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	-23	А	
IDM	Pulsed Drain Current <sup>2</sup>	-75	А	
P₀@Tc=25°C	Total Power Dissipation <sup>4</sup>	22	W	
TSTG	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
R₀JA	Thermal Resistance Junction-ambient <sup>1</sup> 75		°C/W	
R₀JC	Thermal Resistance Junction-Case <sup>1</sup>	Thermal Resistance Junction-Case <sup>1</sup> 4.2		







P-Channel MOSFET



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-20			V
∆BV <sub>DSS</sub> ∕∆T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C ,I⊳=-1mA		-0.012		V/°C
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-10A		12	18	
Rds(on)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-2.5V , I <sub>D</sub> =-8A		16	22	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage		-0.4	-0.7	-1.0	V
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=-250uA$		2.94		mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA
Igss	Gate-Source Leakage Current	V <sub>GS</sub> = ± 12 V , V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-10A		43		S
Qg	Total Gate Charge (-4.5V)			35		
Qgs	Gate-Source Charge	V <sub>DS</sub> =-10V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-10A		5.0		nC
$Q_{gd}$	Gate-Drain Charge			10		
T <sub>d(on)</sub>	Turn-On Delay Time			12.0		
Tr	Rise Time	$V_{DD}$ =-10V , $V_{GS}$ =-4.5V ,		40.0		ns
T <sub>d(off)</sub>	Turn-Off Delay Time	R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-10A		30		115
T <sub>f</sub>	Fall Time			10		
Ciss	Input Capacitance			1400		
Coss	Output Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		350		] pF
Crss	Reverse Transfer Capacitance			300		

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current <sup>1,4</sup>				-50.0	А
lsм	Pulsed Source Current <sup>2,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current				А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C			-1.2	V
trr	Reverse Recovery Time	IF=-10A , dI/dt=100A/µs ,		27		nS
Qrr	Reverse Recovery Charge	T <sub>J</sub> =25℃		17.8		nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

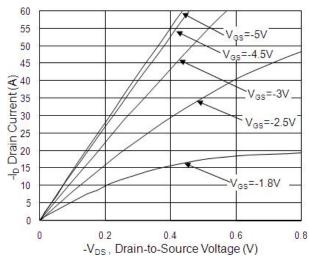
2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq 2\%$ 

3. The power dissipation is limited by 150°C junction temperature

4. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications , should be limited by total power dissipation.



#### **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

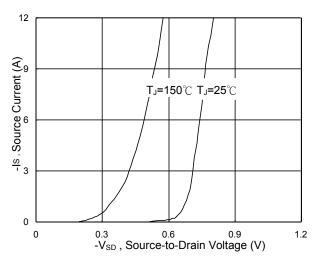


Fig.3 Forward Characteristics of Reverse

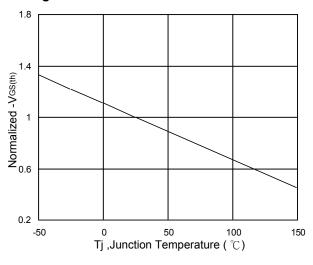


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

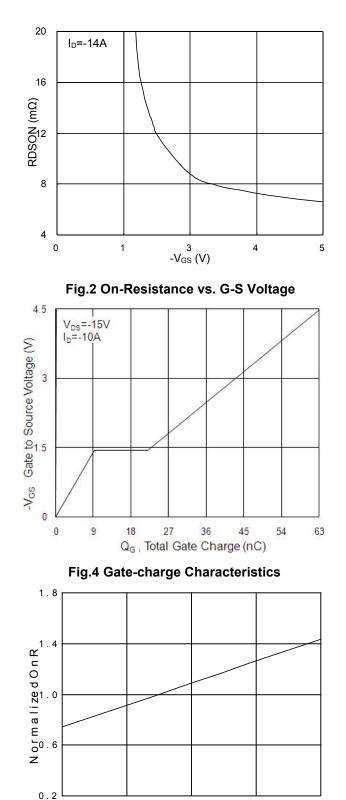


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>

50

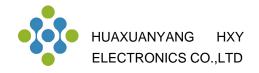
T<sub>J</sub>, Junction Temp<sup>®</sup>(e)

100

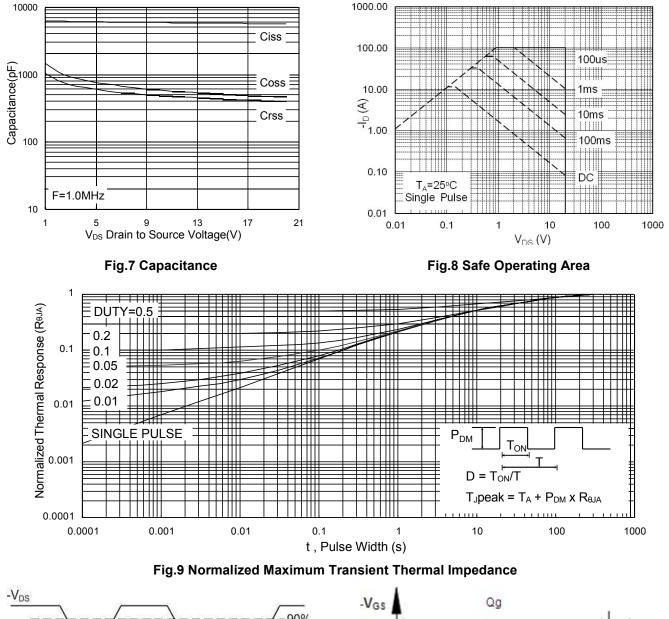
- 5 0

0

150



# HXY50P02D P-Channel Enhancement Mode MOSFET



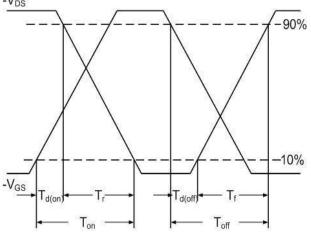
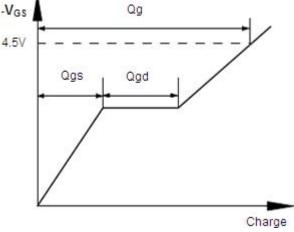


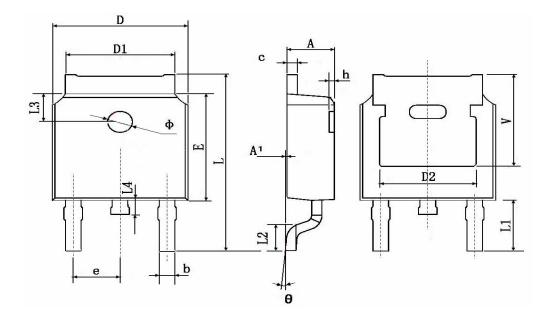
Fig.10 Switching Time Waveform



#### Fig.11 Gate Charge Waveform



# TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches			
	Min.	Max.	Min.	Max.		
A	2.200	2.400	0.087	0.094		
A1	0.000	0.127	0.000	0.005		
b	0.660	0.860	0.026	0.034		
С	0.460	0.580	0.018	0.023		
D	6.500	6.700	0.256	0.264		
D1	5.100	5.460	0.201	0.215		
D2	4.830 TYP.		0.190 TYP.			
E	6.000	6.200	0.236	0.244		
е	2.186	2.386	0.086	0.094		
L	9.800	10.400	0.386	0.409		
L1	2.900	) TYP.	0.114 TYP.			
L2	1.400	1.700	0.055	0.067		
L3		1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039		
Φ	1.100	1.300	0.043	0.051		
θ	0 °	8°	0°	8°		
h	0.000	0.300	0.000	0.012		
V	5.350	5.350 TYP. 0.211 TYP.				



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